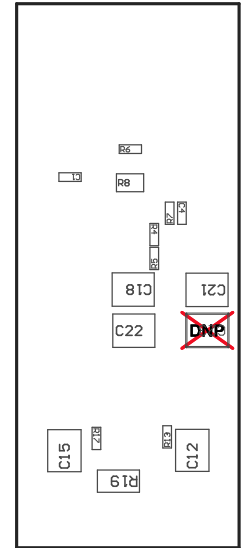


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 002

|                                  |                                  |        |                                |
|----------------------------------|----------------------------------|--------|--------------------------------|
| PCB VIEWED FROM TOP SIDE         | BOARD #: PMP20807                | REV: A | SVN REV: Not In VersionControl |
|                                  |                                  |        |                                |
| PLOT NAME = Top Assembly Drawing | GENERATED : 5/31/2017 1:10:28 PM |        | TEXAS INSTRUMENTS              |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 002

|                                     |                                  |        |                                |
|-------------------------------------|----------------------------------|--------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE         | BOARD #: PMP20807                | REV: A | SVN REV: Not In VersionControl |
|                                     |                                  |        |                                |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 5/31/2017 1:10:32 PM |        | TEXAS INSTRUMENTS              |

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